

NOVASTACK® 35-HDN

Ideal for 5G mmWave antenna module and devices, fully-shielded and narrow design, Power supply is available with Corson Alloy contact, 0.35 mm pitch, 0.7 mm height

Product Specifications:

Board Pitch (mm)	0.35	
Wiping Length (mm)	0.14	
Mated Size (mm)	Height	0.7 +/- 0.05
	Width	Formula: 4.15 (10 P), 5.90 (20 P), 7.90 (30 P)
	Depth	2.15 mm
Frequency	DC ~ 15 GHz	
Current Rating	Signal	1.0 A / pin (Max. 10 P) (12 P and over : 12.0 A AC/DC (Total))
	Power	-
Pin Counts	Range	10 - 60
	Available	10, 20, 30

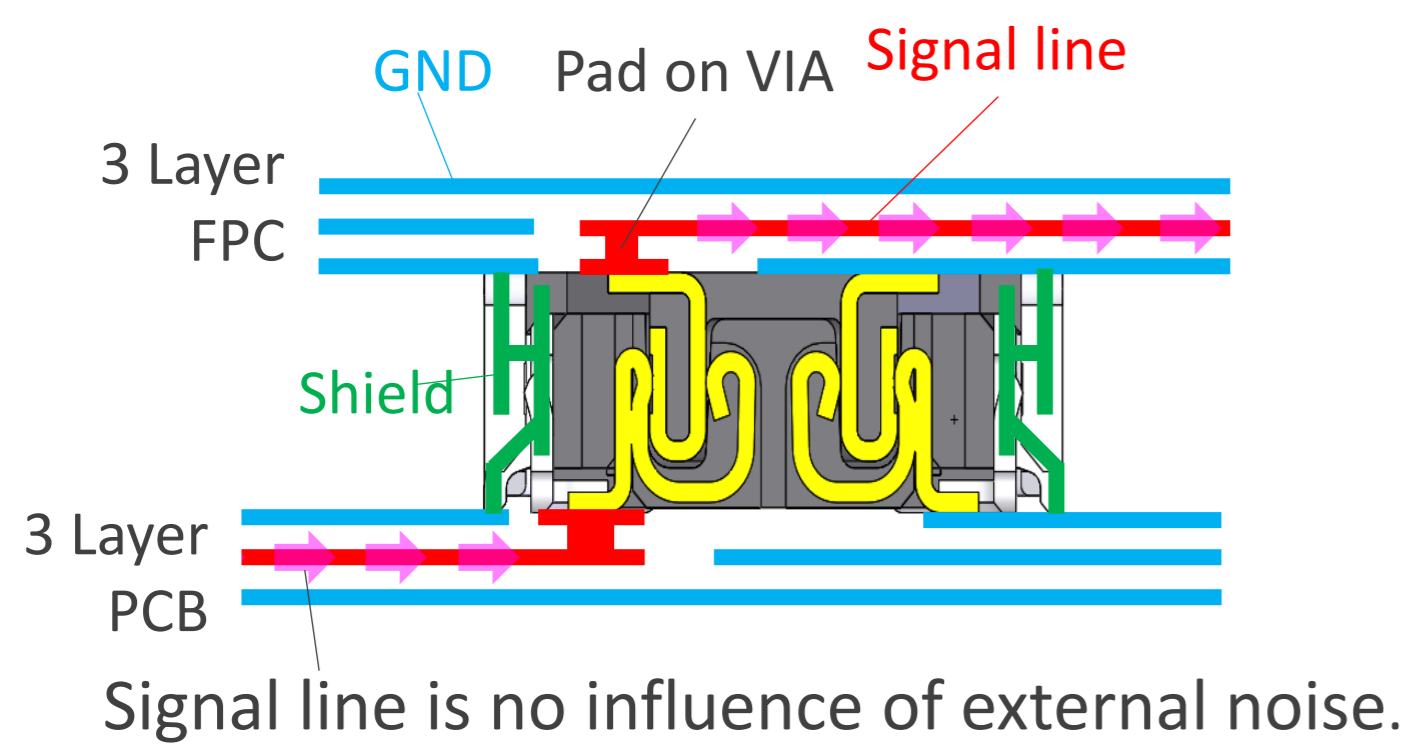
Applicable Standards (Reference Only):

USB4 (20 Gbps/lane) USB 3.1 Gen 2 (10 Gbps)

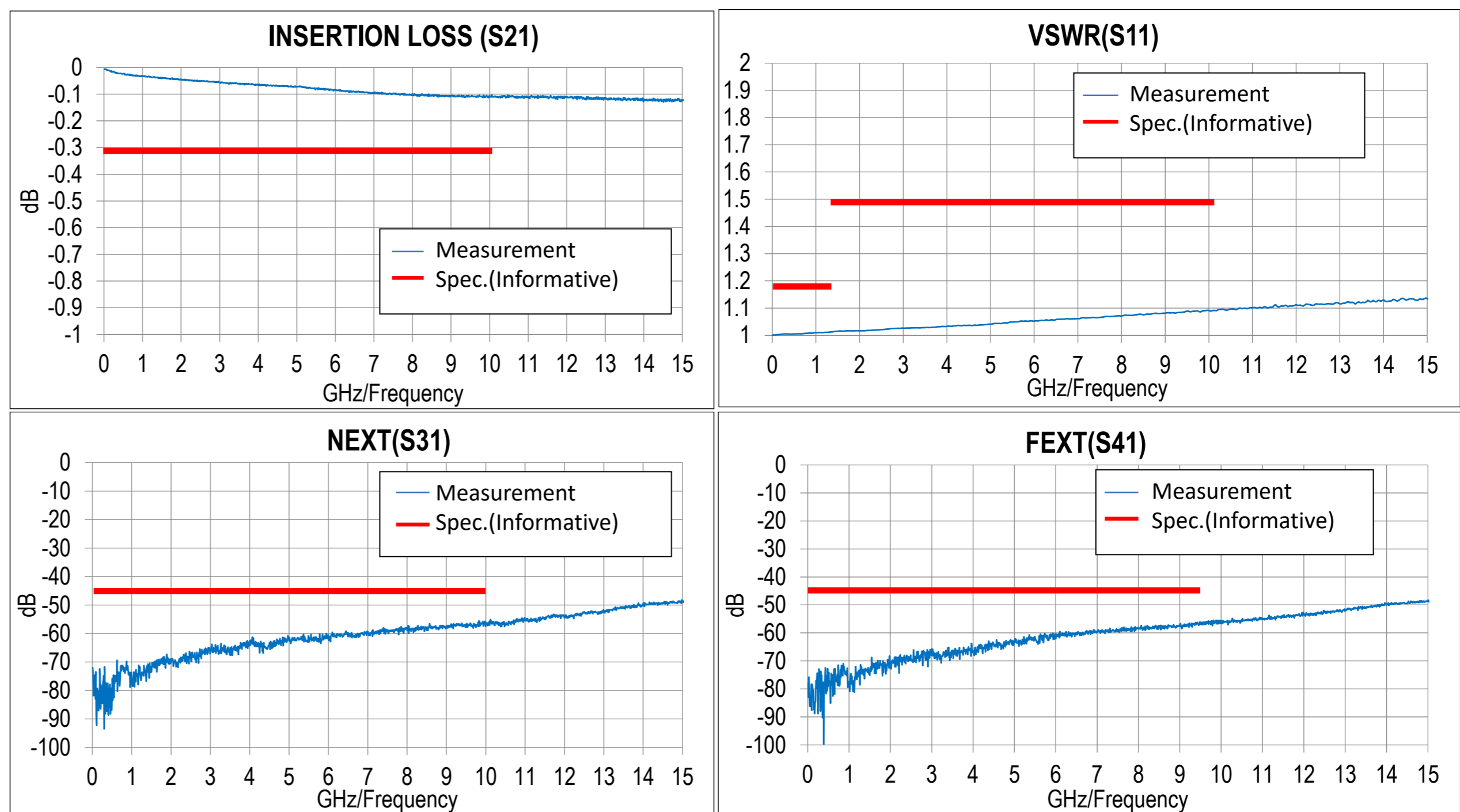
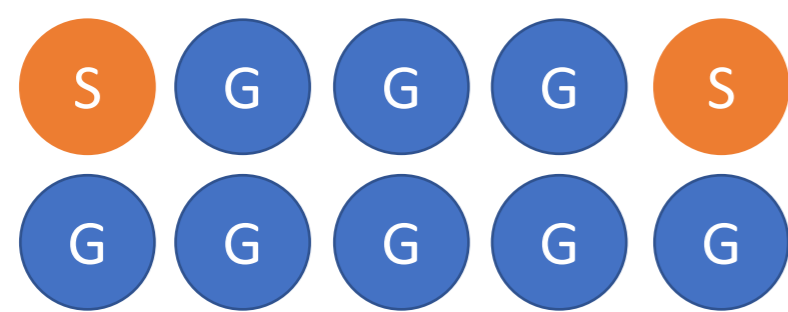
* Please inquire for pin counts not listed or outside of the pin count range.



► Ideal for high frequency applications (5G mmWave, USB4 / Thunderbolt 4, etc.)

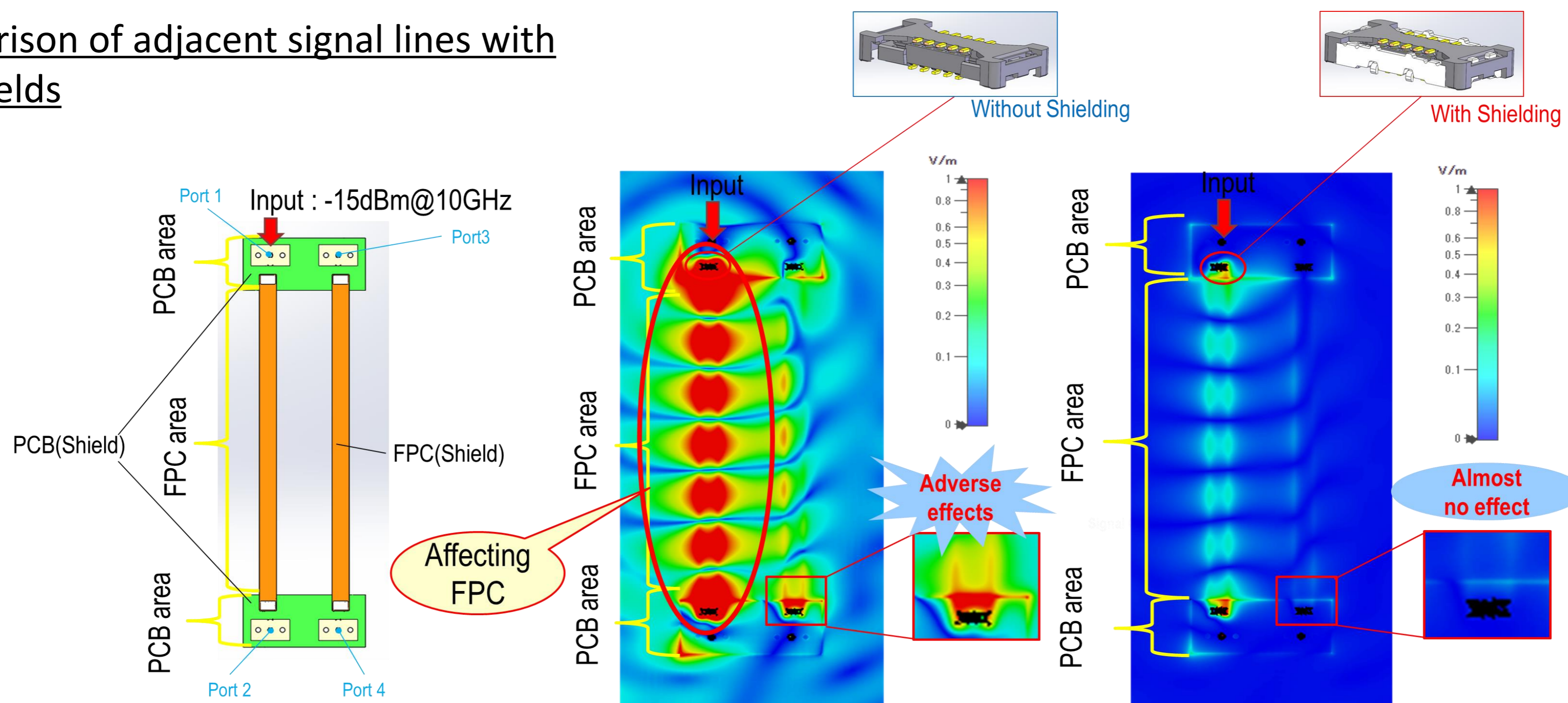


◆ Pin assignment



► ZenShield® fully-shielded design, decreases EMI issue caused by 5G applications

E-Field comparison of adjacent signal lines with or without shields



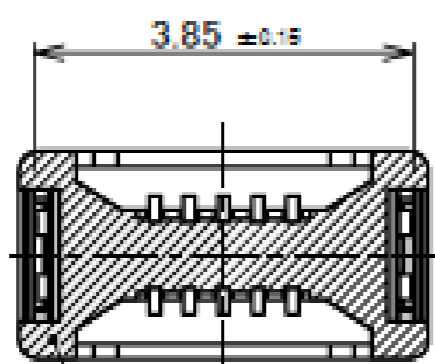
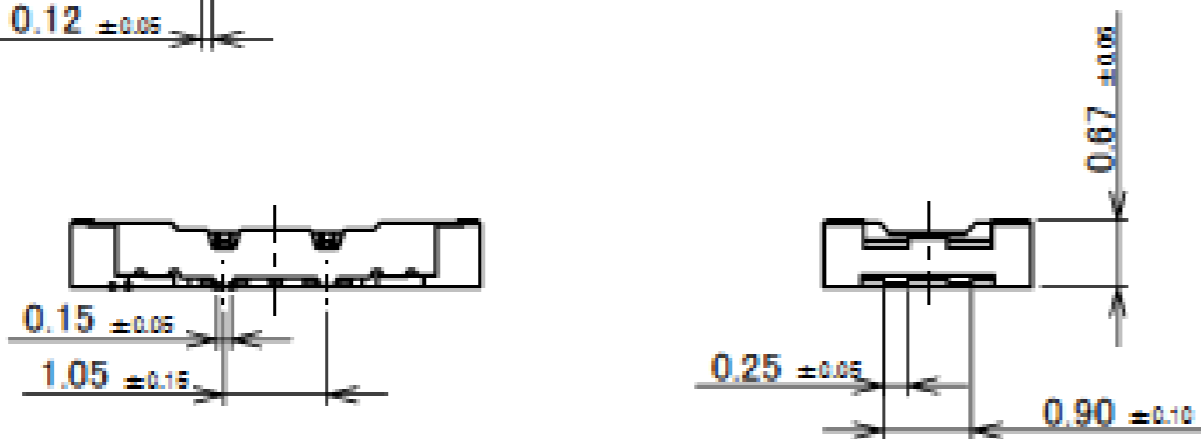
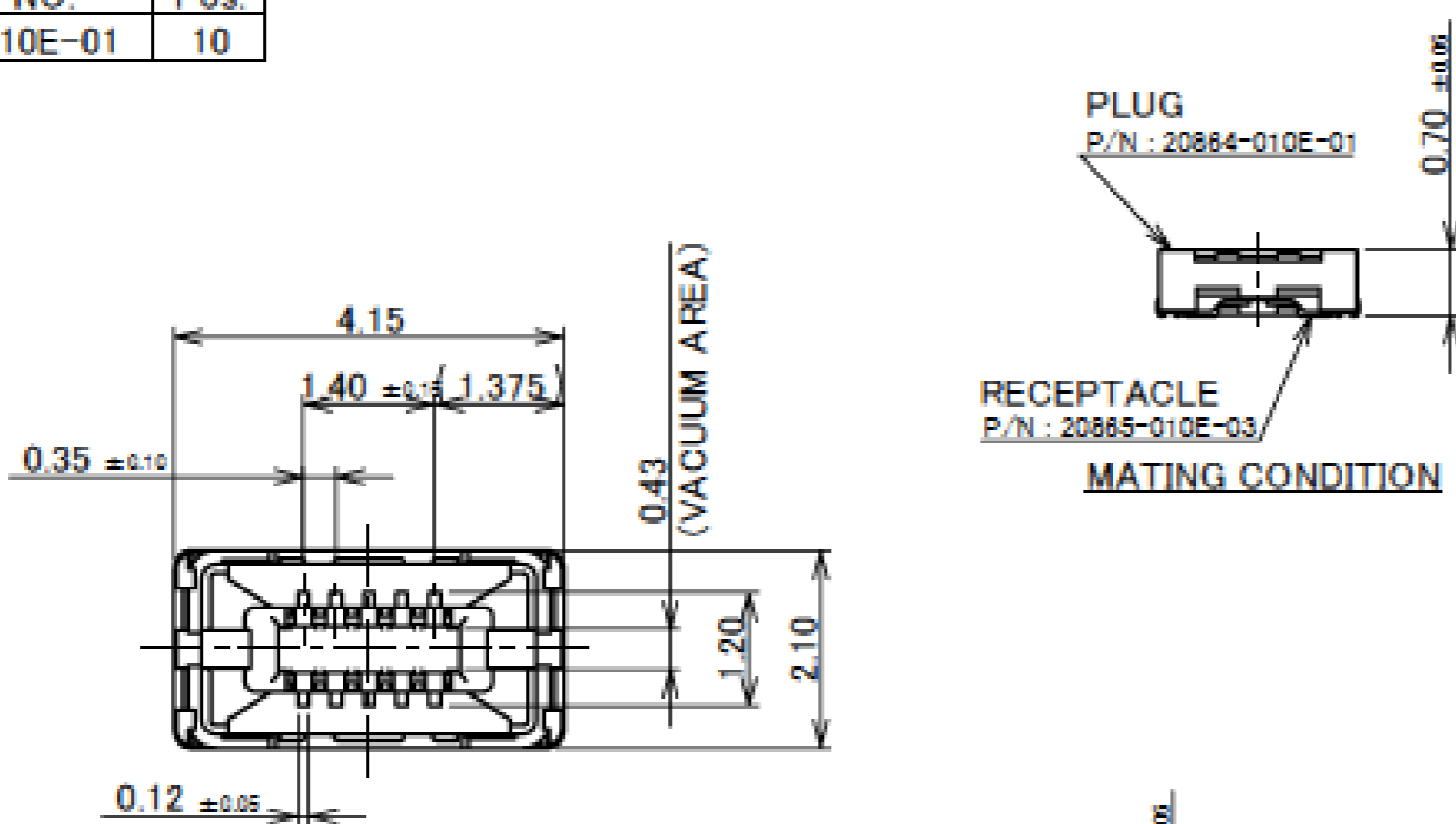
► Narrow depth and low height, fully-shielded board-to-board connector



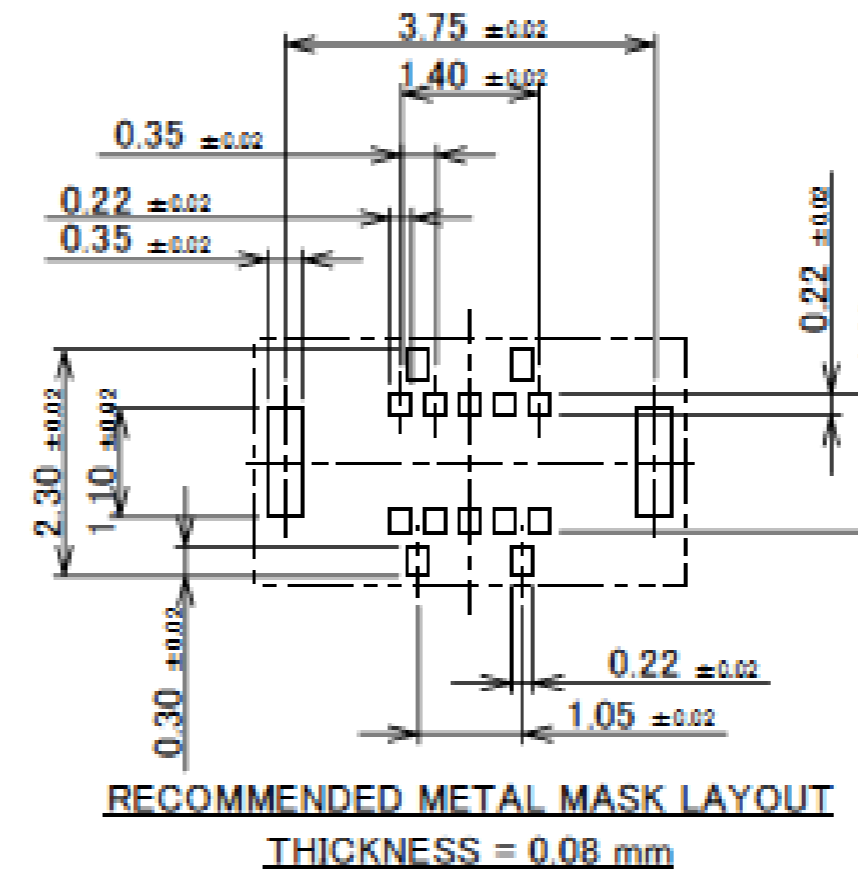
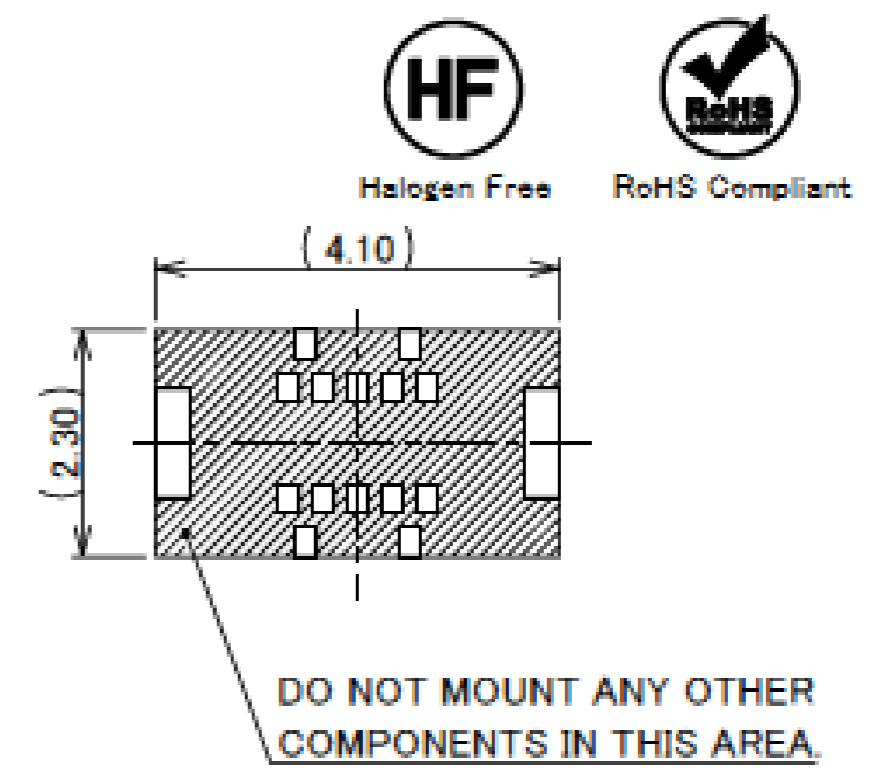
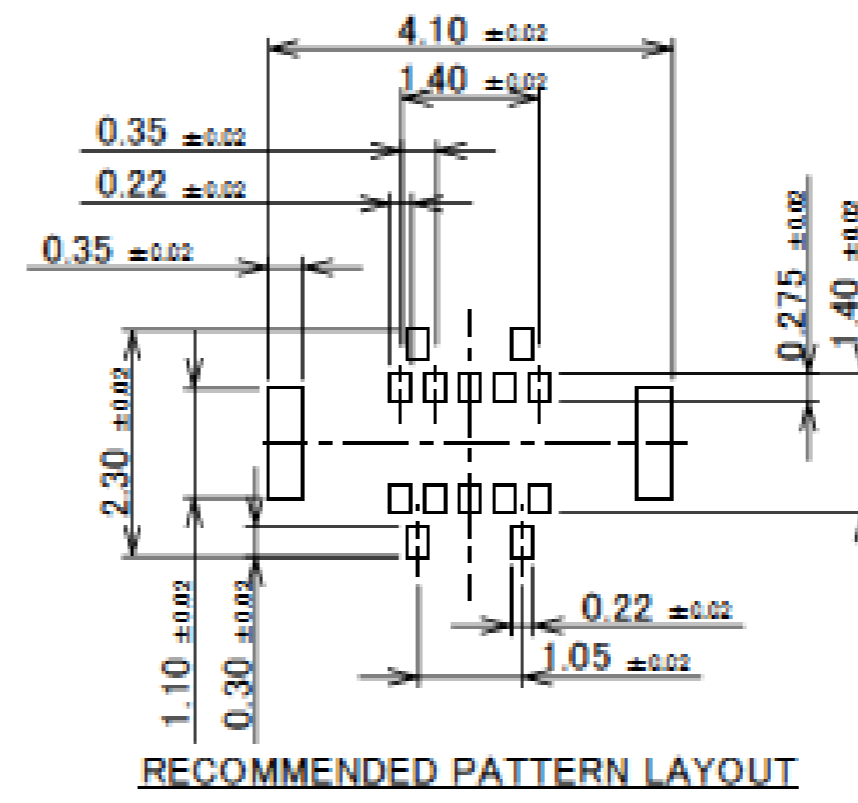
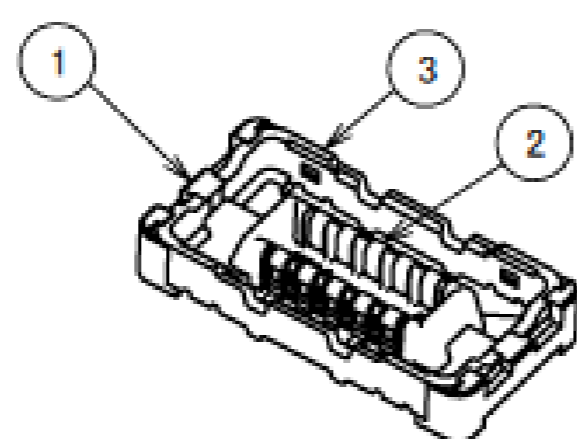
Component Parts Detail

Plug Assembly

Recommended P/N	20864-010E-01
PART NO.	Pos.
20864-010E-01	10



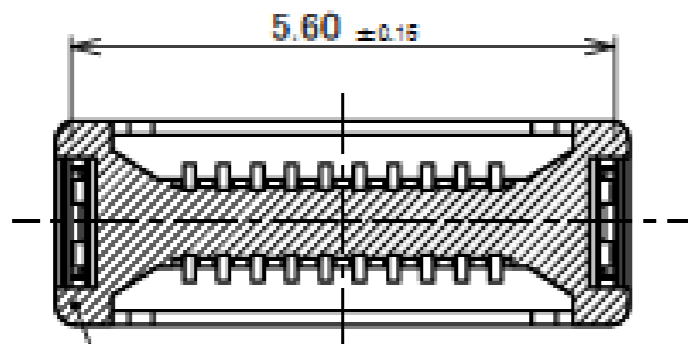
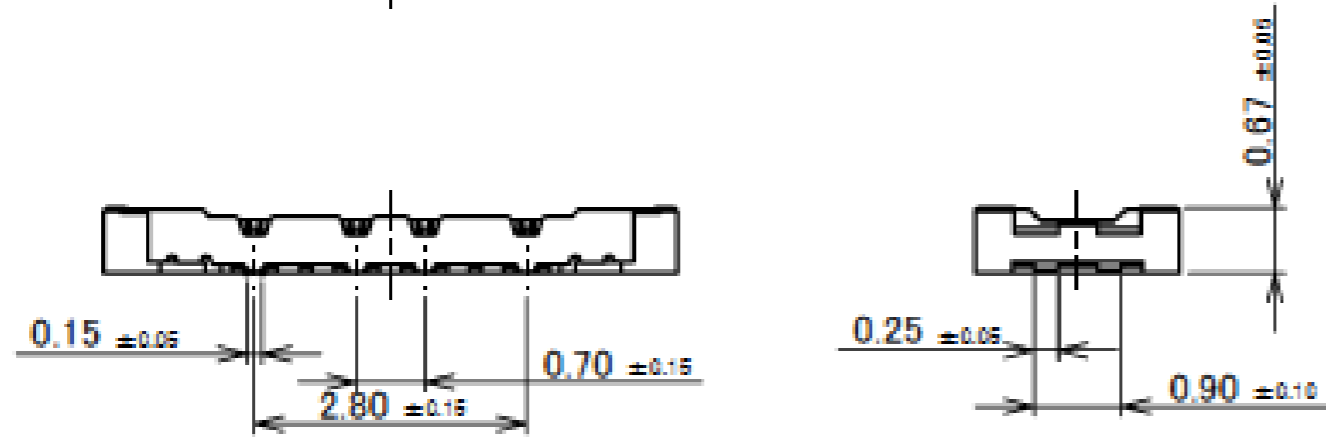
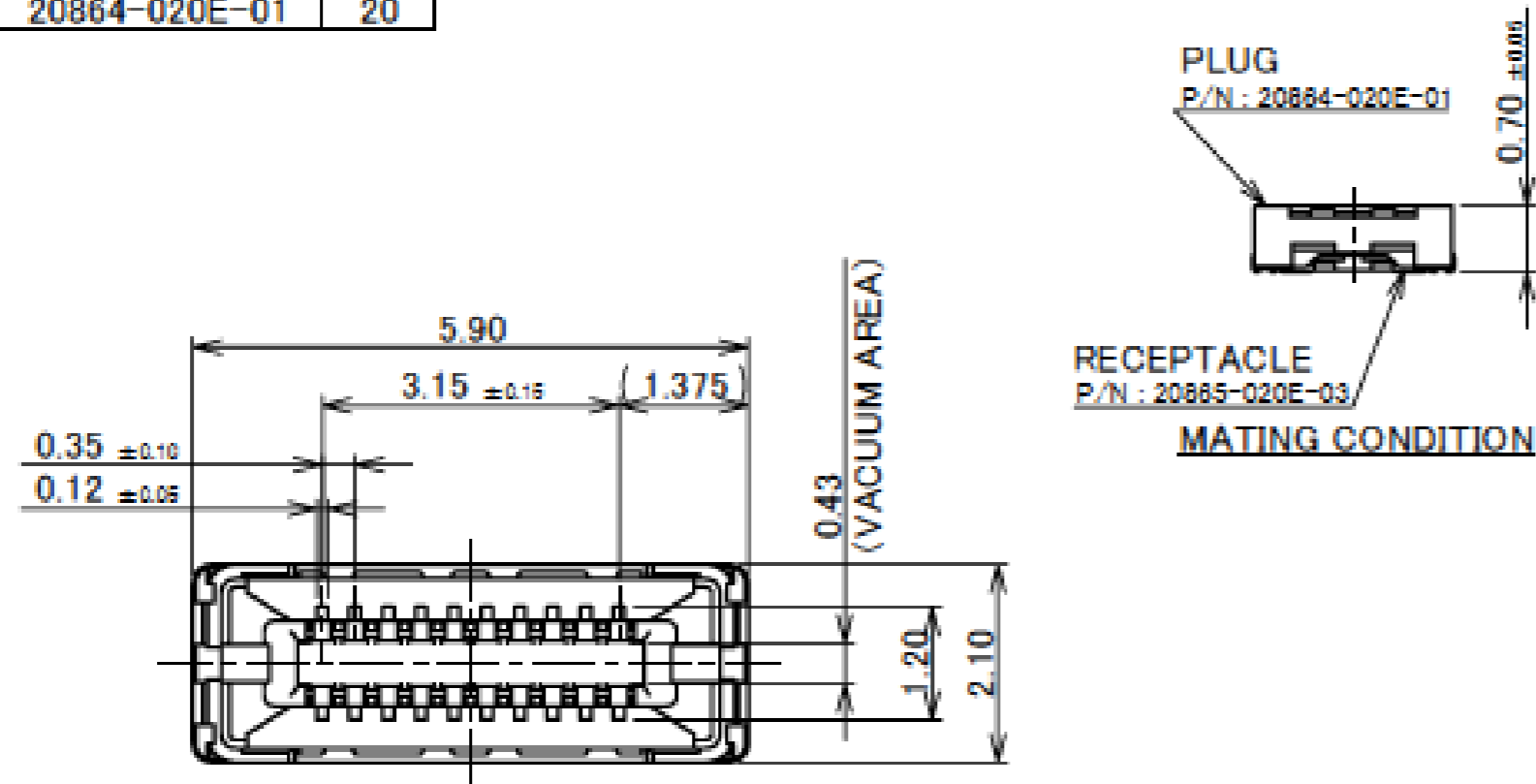
There is a possibility of dent shape in the bottom surface of HOUSING.



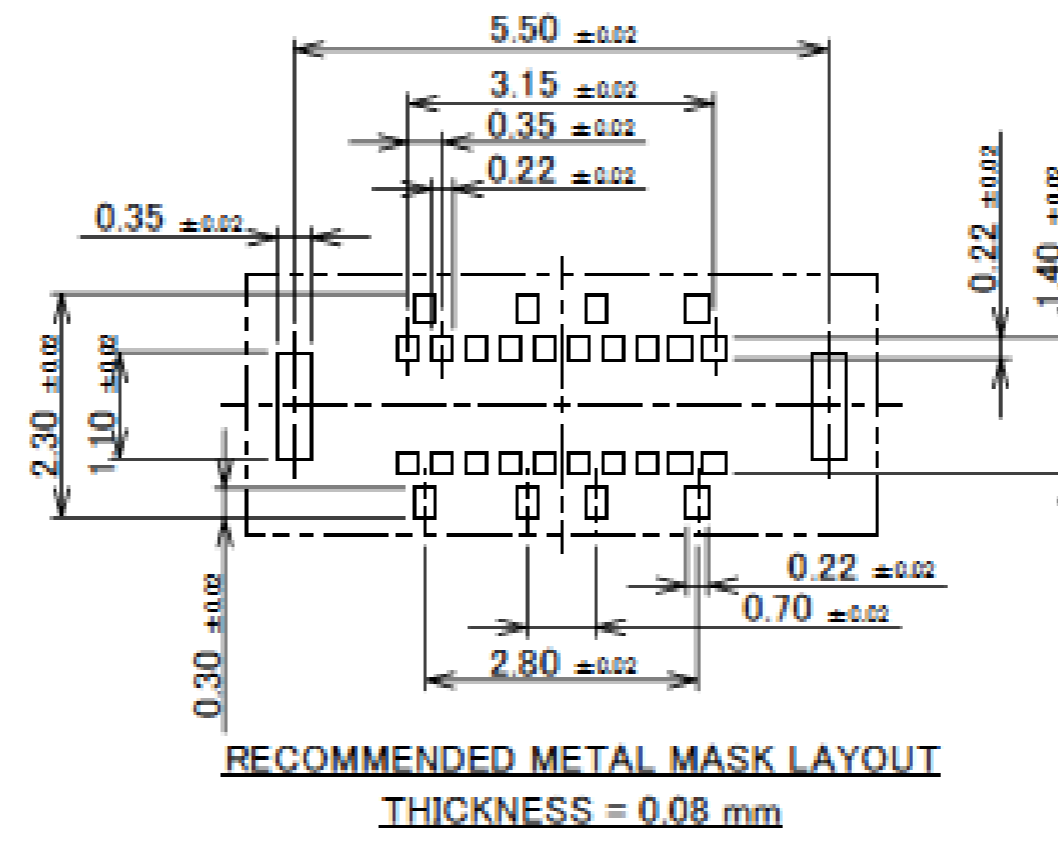
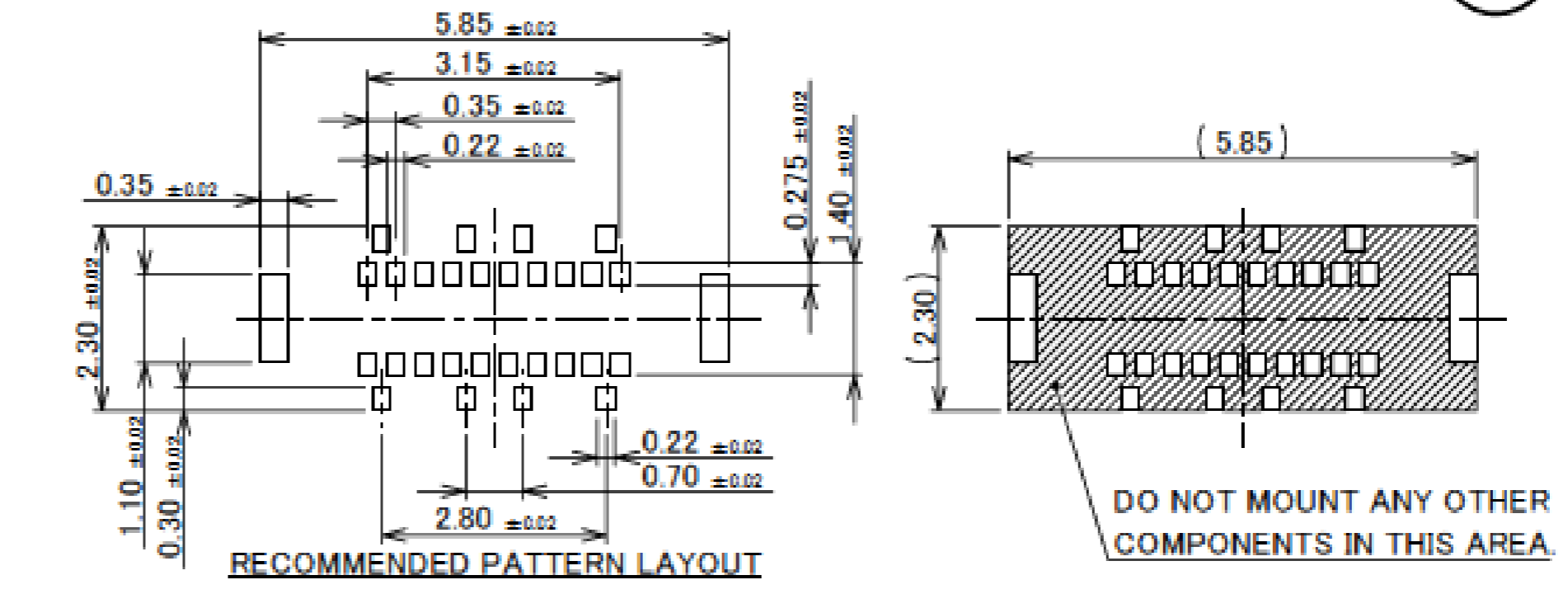
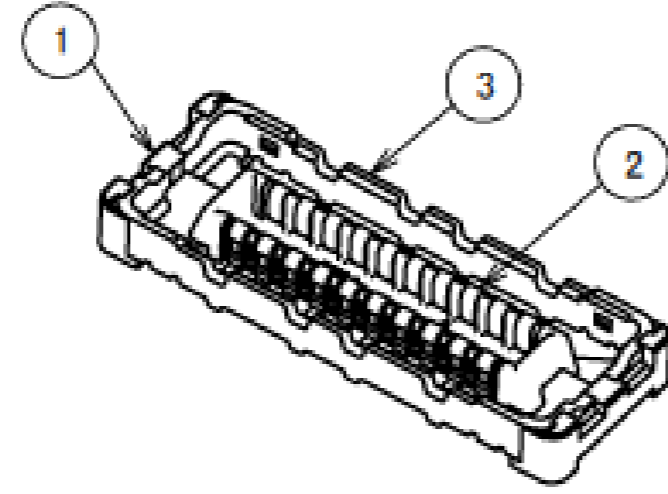
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS
3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0, BLACK

Plug Assembly

Recommended P/N		20864-020E-01
PART NO.	Pos.	
20864-020E-01	20	



There is a possibility of dent shape in the bottom surface of HOUSING.

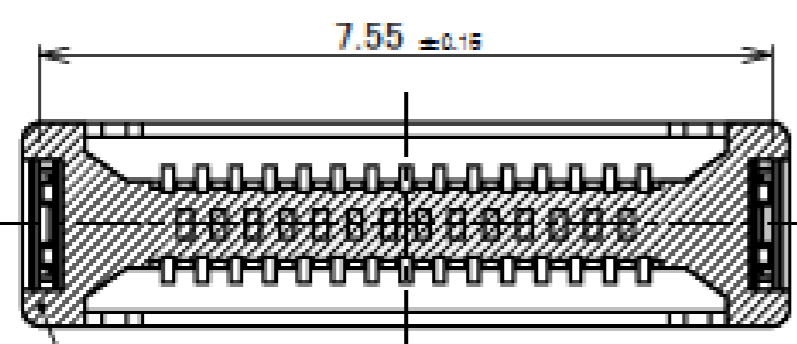
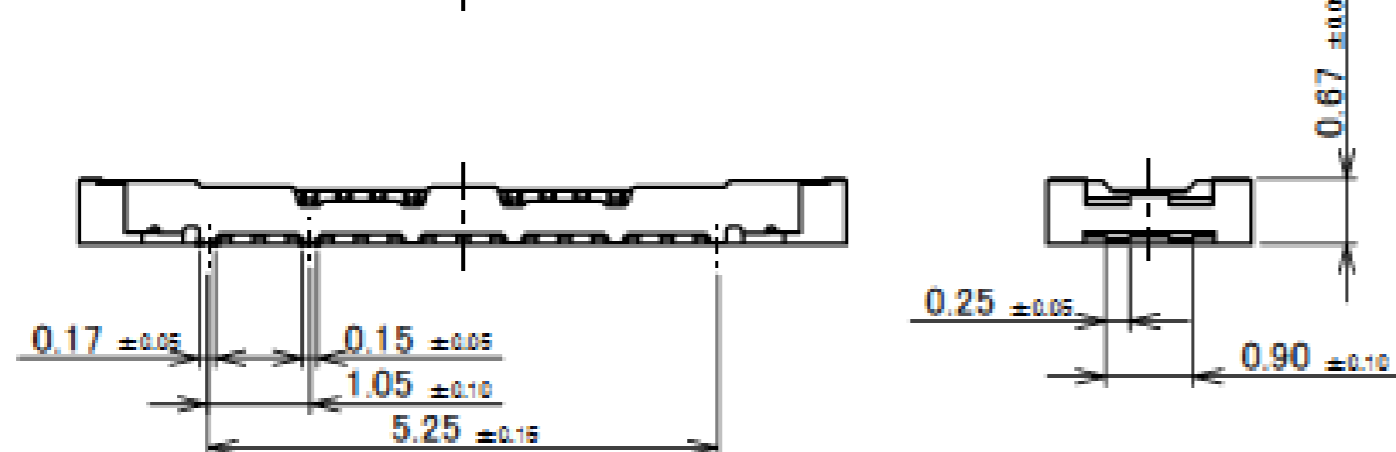
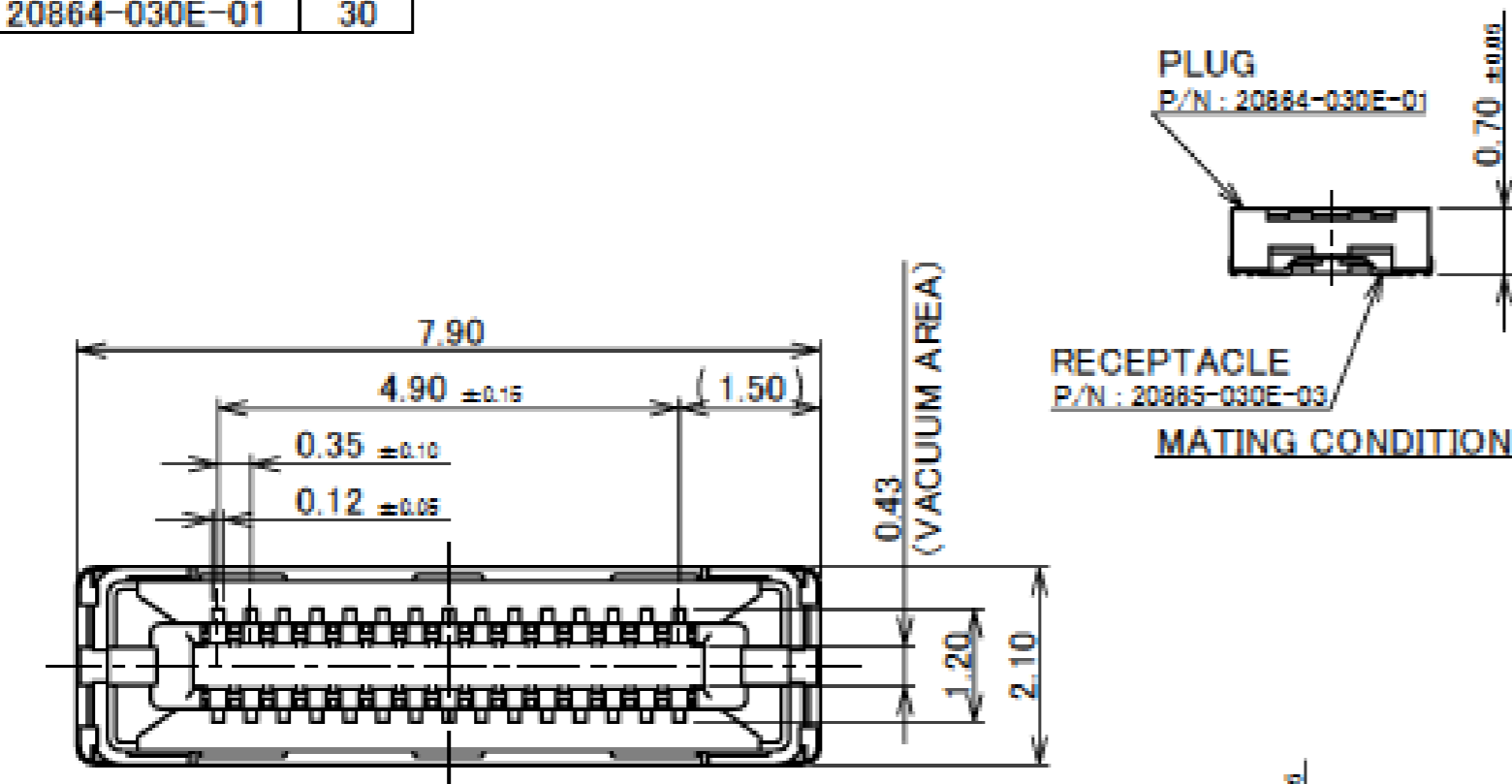


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1	HOUSING	LCP	UL94V-0, BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS

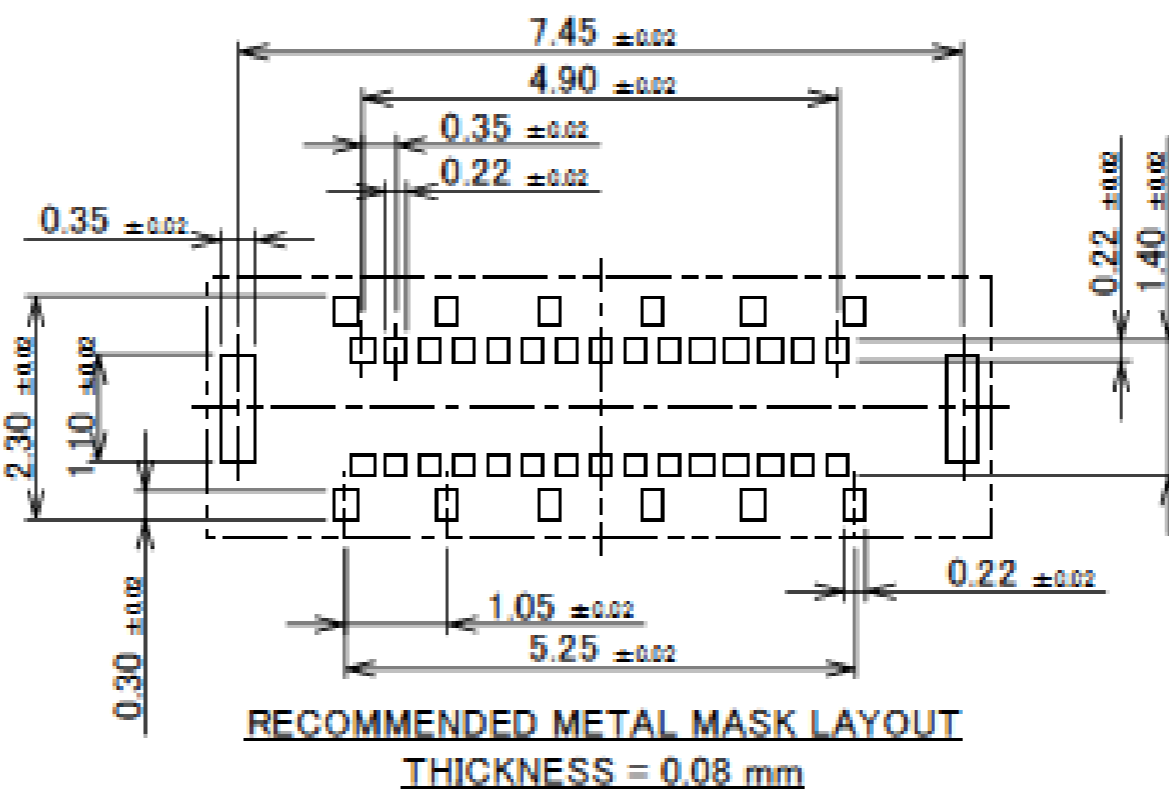
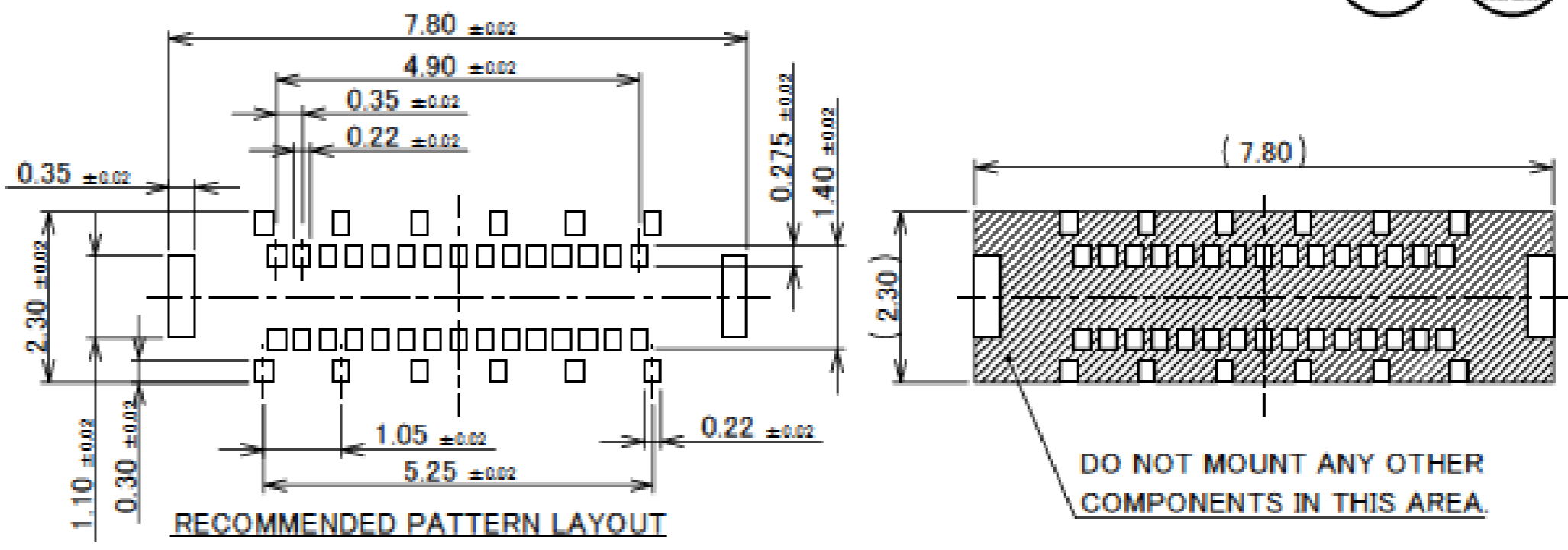
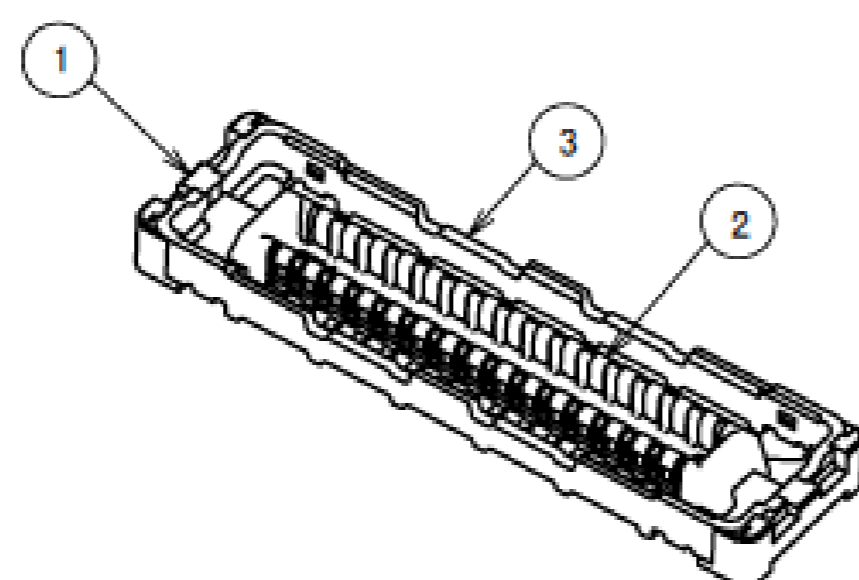


Rev.9

Recommended P/N		20864-030E-01
PART NO.	Pos.	
20864-030E-01	30	



There is a possibility of dent shape in the bottom surface of HOUSING.

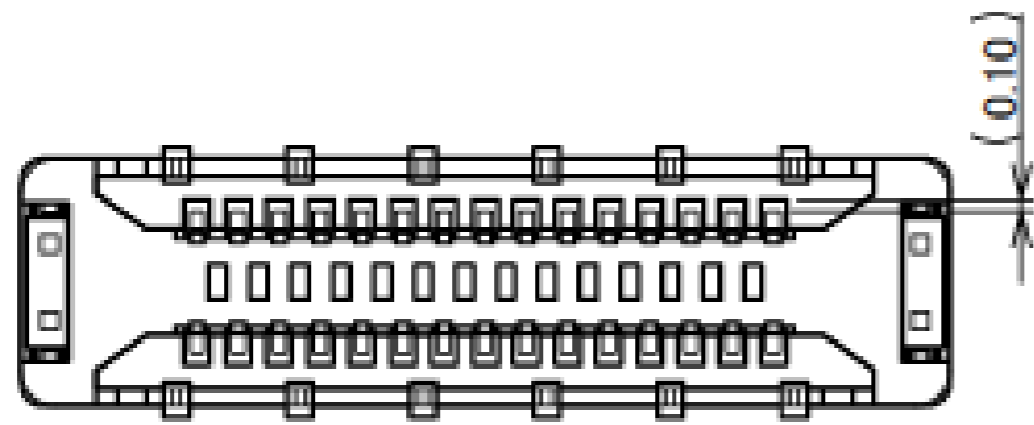


3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0, BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS

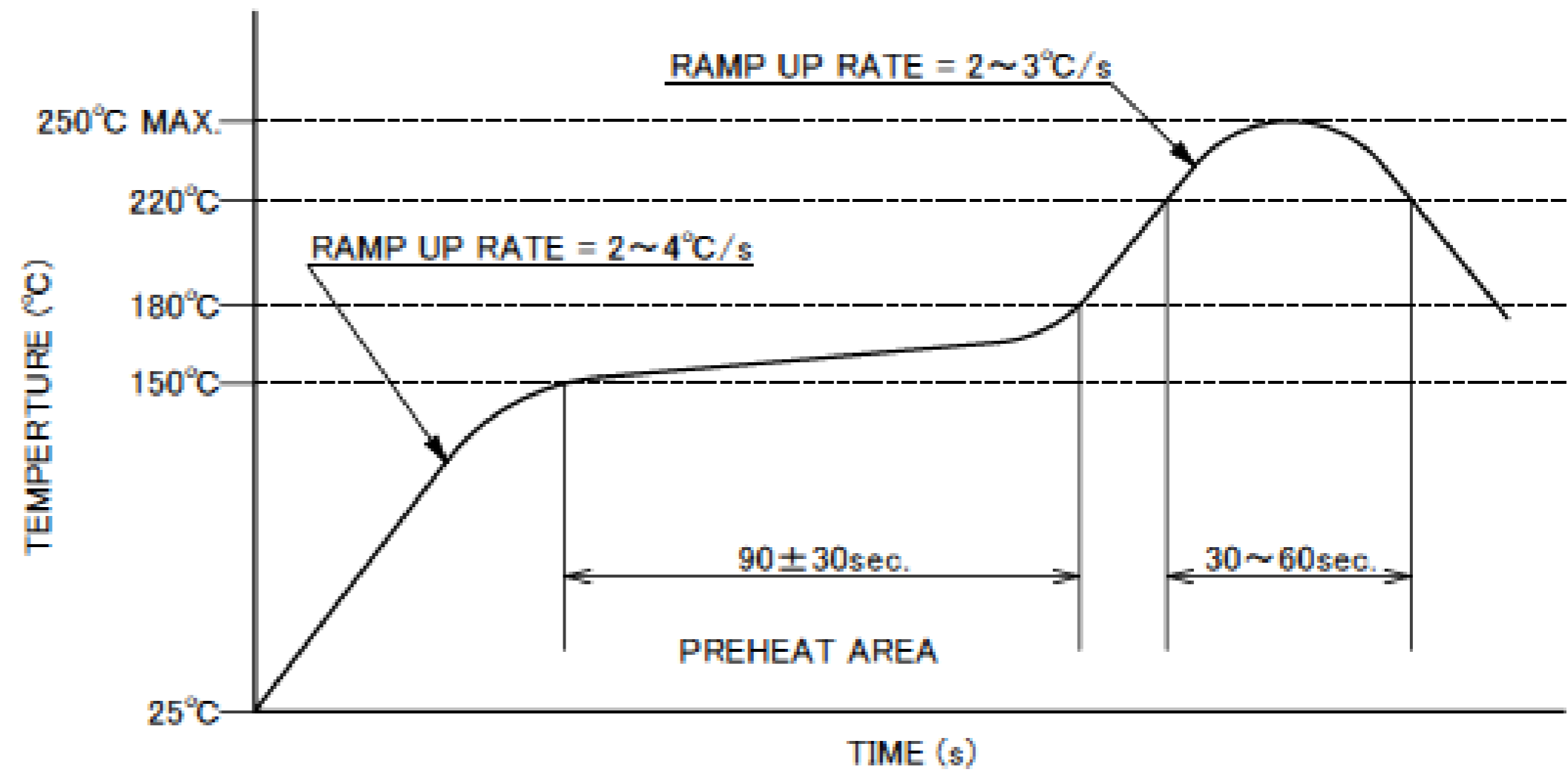


Rev.9

Plug Assembly



CONNECTOR ON RECOMMENDED FOOTPRINT PATTERN



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

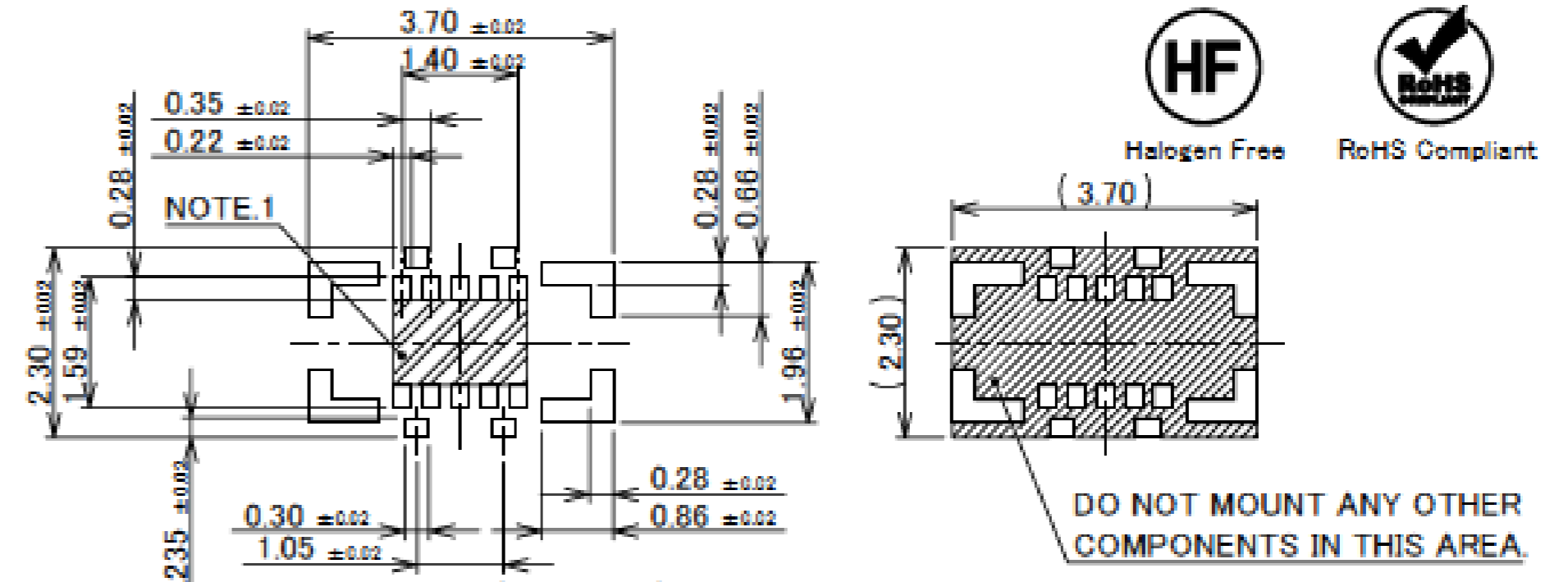
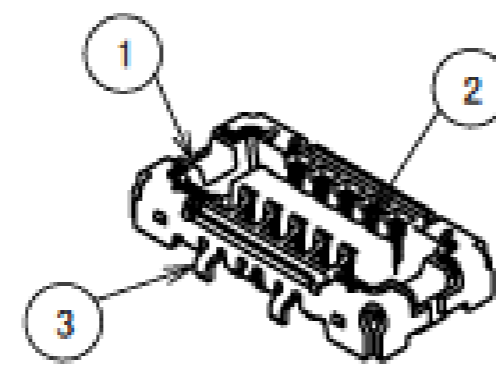
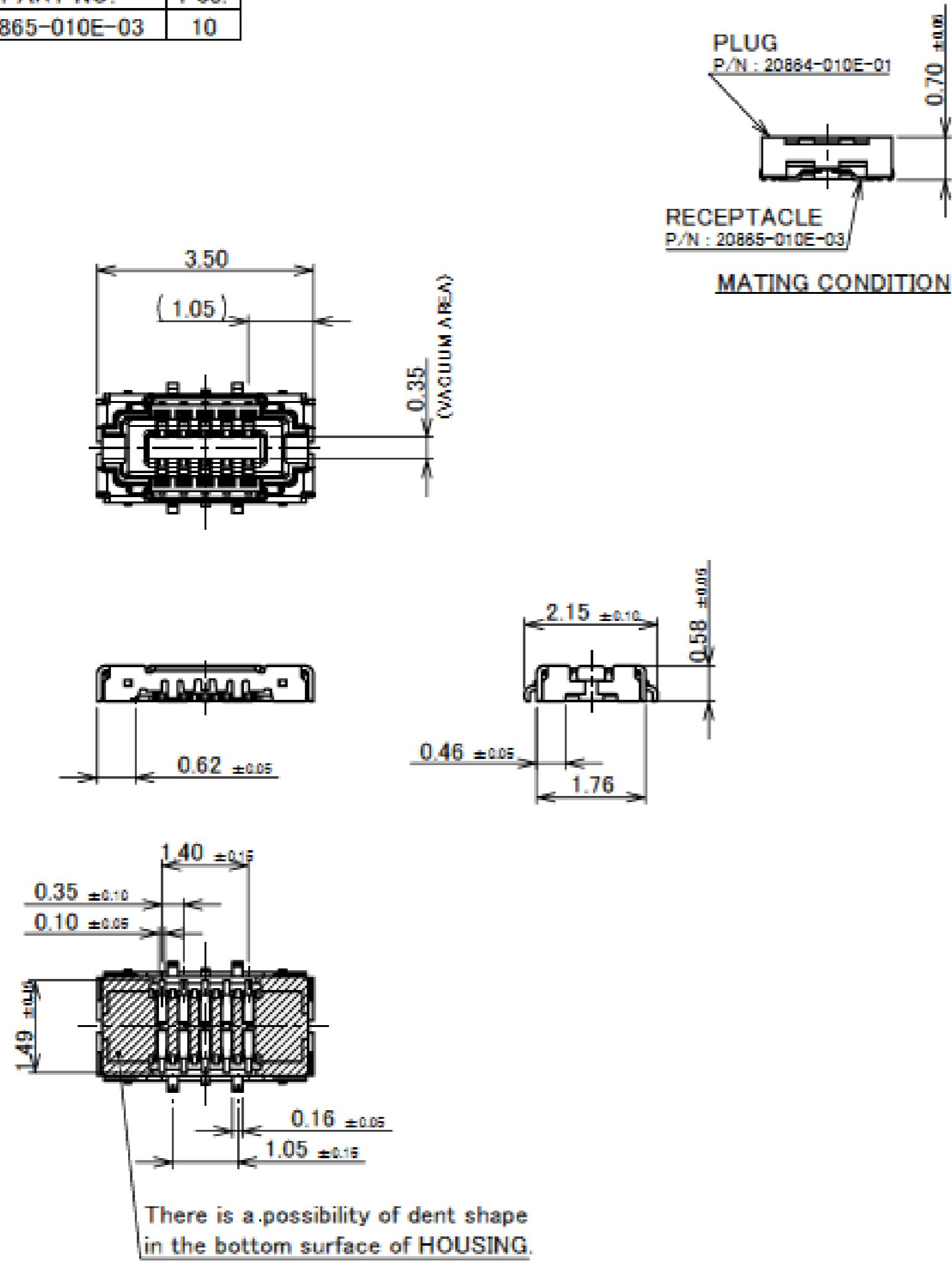
Rev.9

ITEMS	SPECIFICATION
APPLICABLE CONNECTOR PART No.	20865-0**E-**
RATING VOLTAGE	60V AC(r.m.s) / DC (PER CONTACT PIN)
RATING AMPERAGE (FOR SIGNAL CONTACT)	10P:1.0 A MAX. AC/DC x PIN COUNTS = 10.0 A (TOTAL) 12P AND OVER : 12.0 A AC/DC (TOTAL)
OPERATING TEMPERATURE	233~358K(-40°C~85°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENSING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 40mohm MAX. / AFTER TEST : $\leq 40\text{mohm}$ MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : $\leq 20\text{mohm}$ MAX.
INSULATION RESISTANCE	INITIAL : 1,000Mohm MIN. / AFTER TEST : 500Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	10 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	INITIAL 2.0N/Pin MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	10 CYCLES 0.15N/Pin MIN.
COPLANARITY	0.08 MAX
PRODUCT SPECIFICATION	PRS-2607
TEST REPORT	TR-19055
PACKING STANDARD	PST-18022
INSTRUCTION MANUAL	HIM-18019
APPEARANCE CRITERIA No.	QLS-A***

Rev.9

Receptacle Assembly

Recommended P/N		20865-010E-03
PART NO.	Pos.	
20865-010E-03	10	

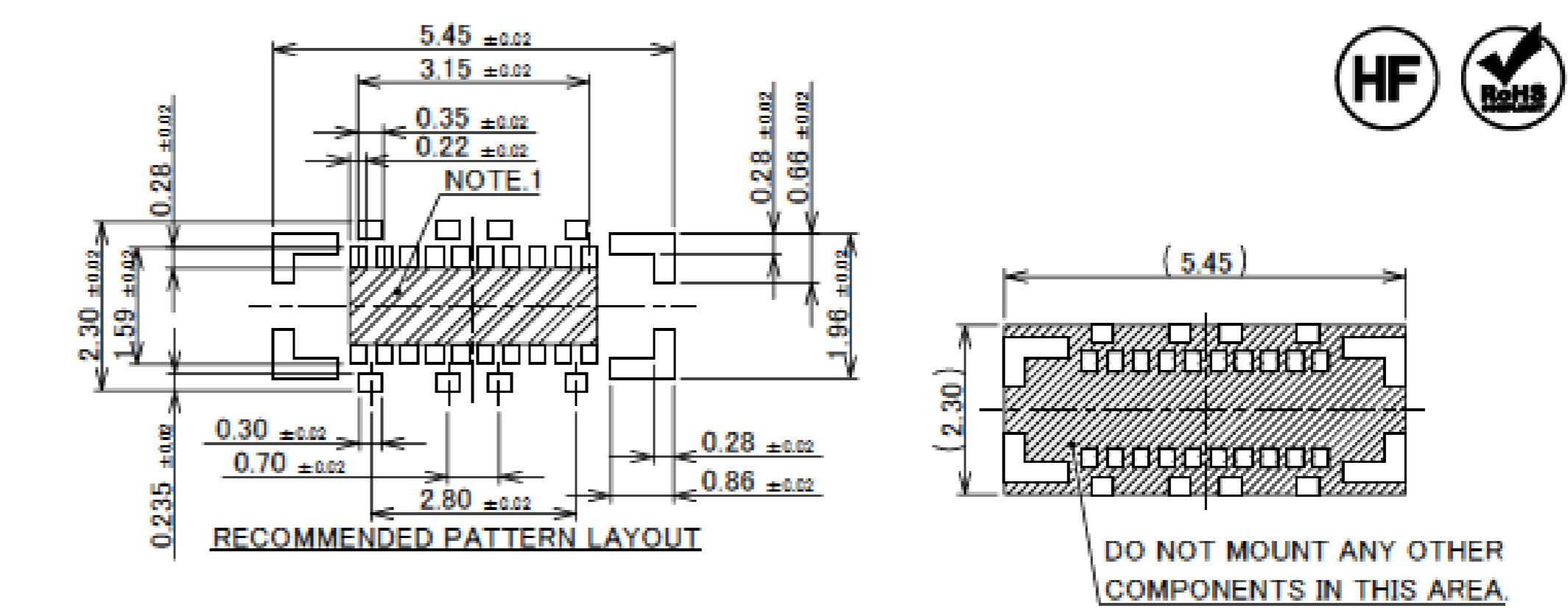
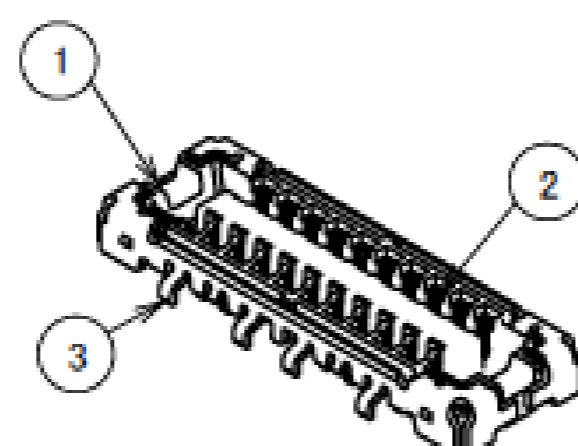
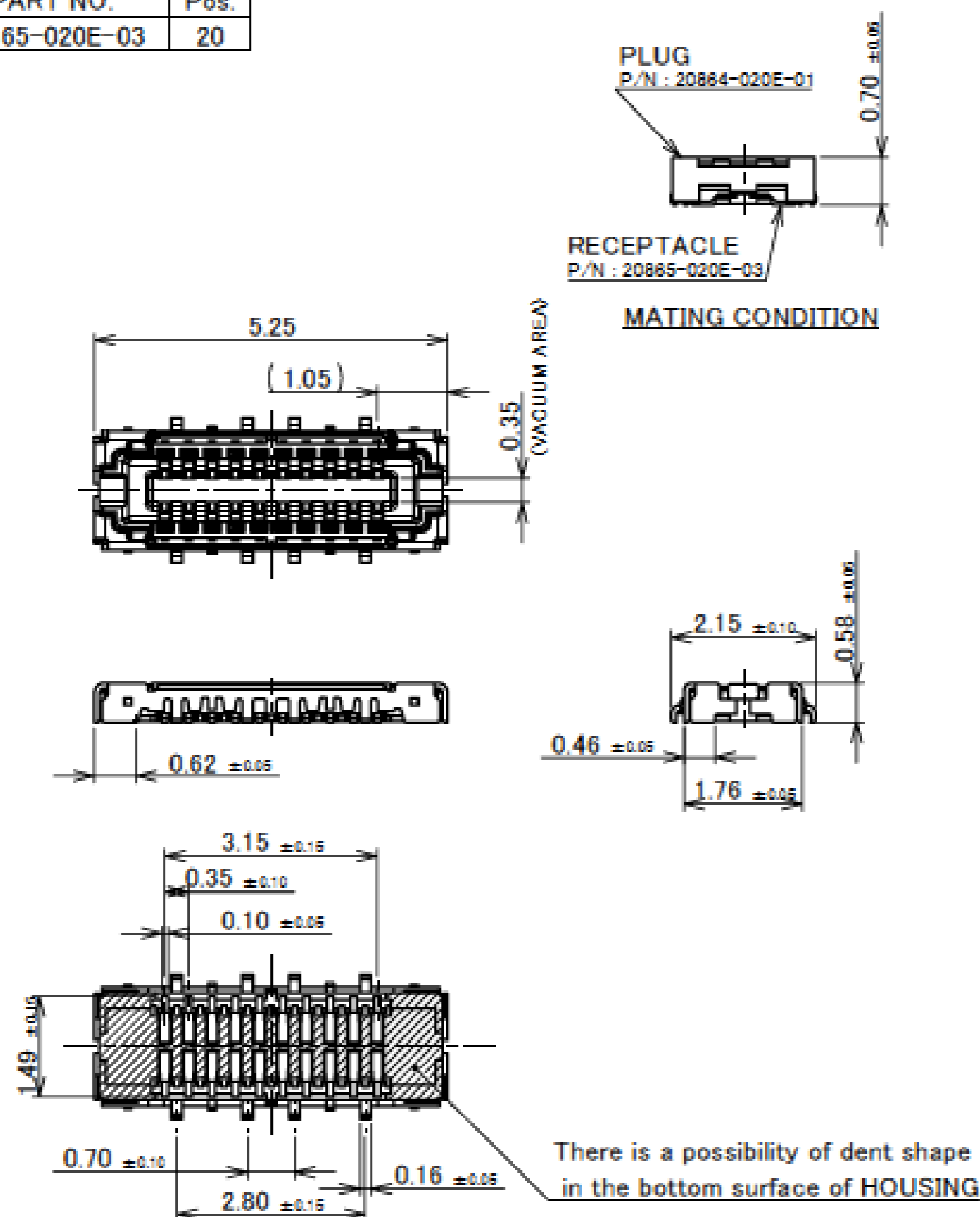


NOTES.
1. FOOT PRINT PATTERN PROHIBITION AREA :
SOLDER RESIST MUST BE APPLIED TO THIS HATCHED AREA
IF SURFACE TRACES ARE ROUNDED.

NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS
3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
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1	HOUSING	LCP	UL94V-0 BLACK

Rev.9

Recommended P/N		20865-020E-03
PART NO.	Pos.	
20865-020E-03	20	



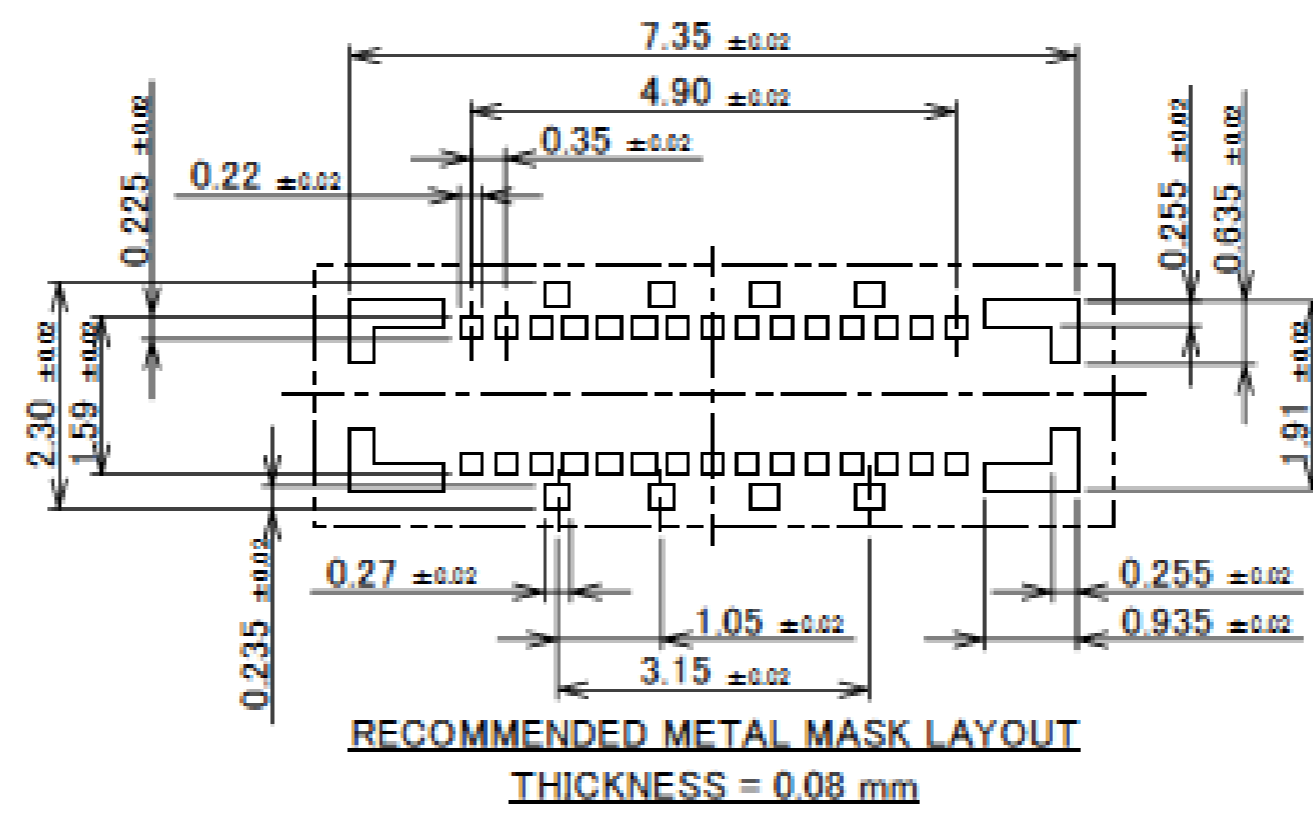
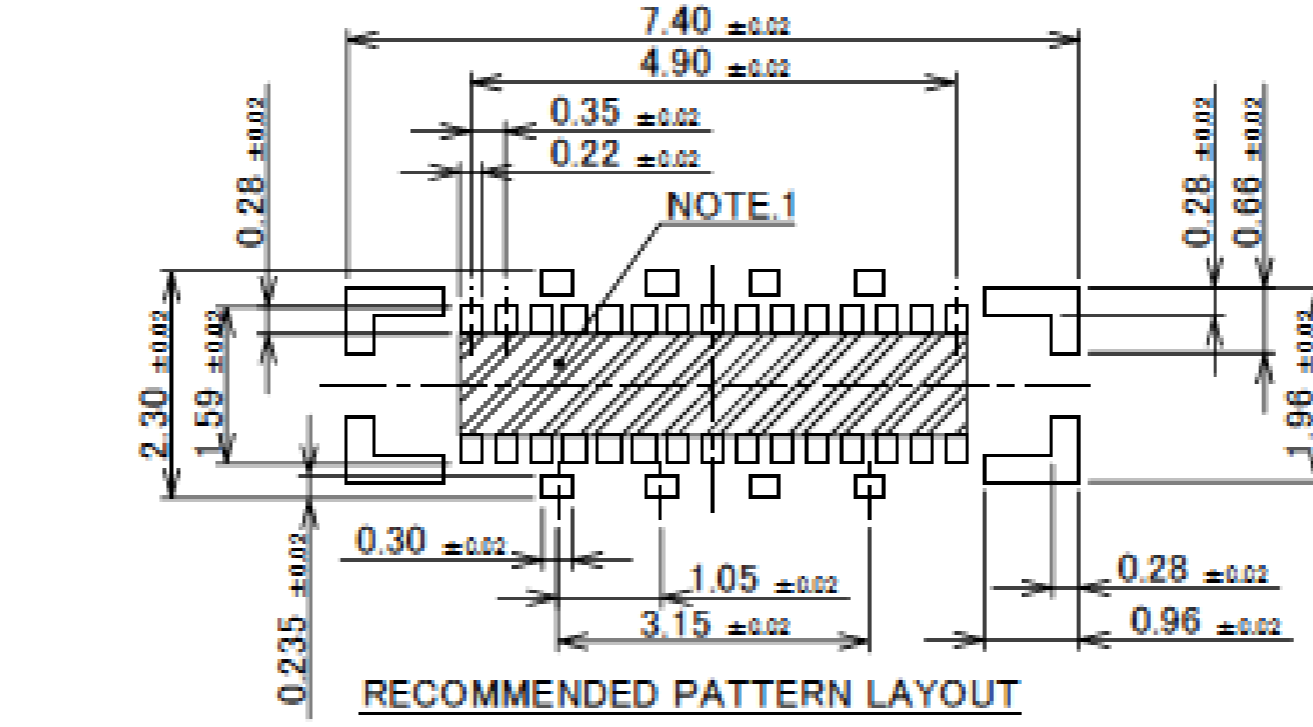
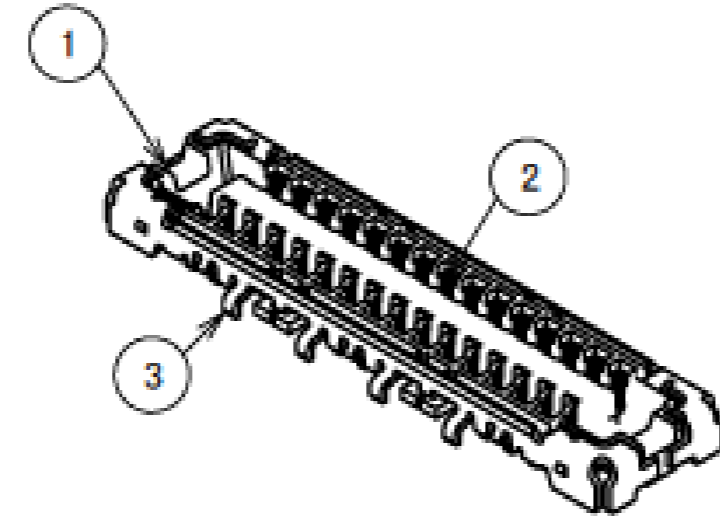
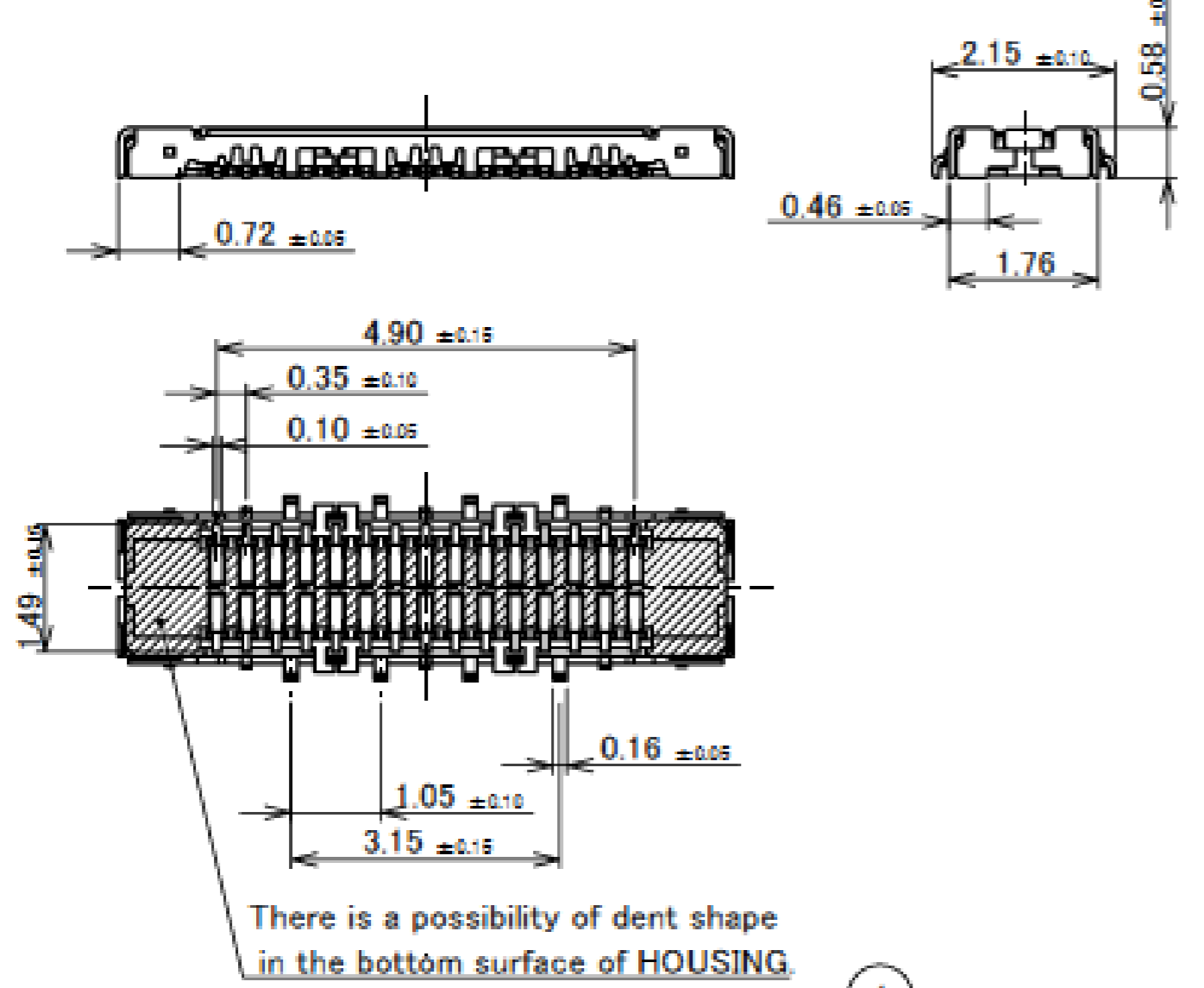
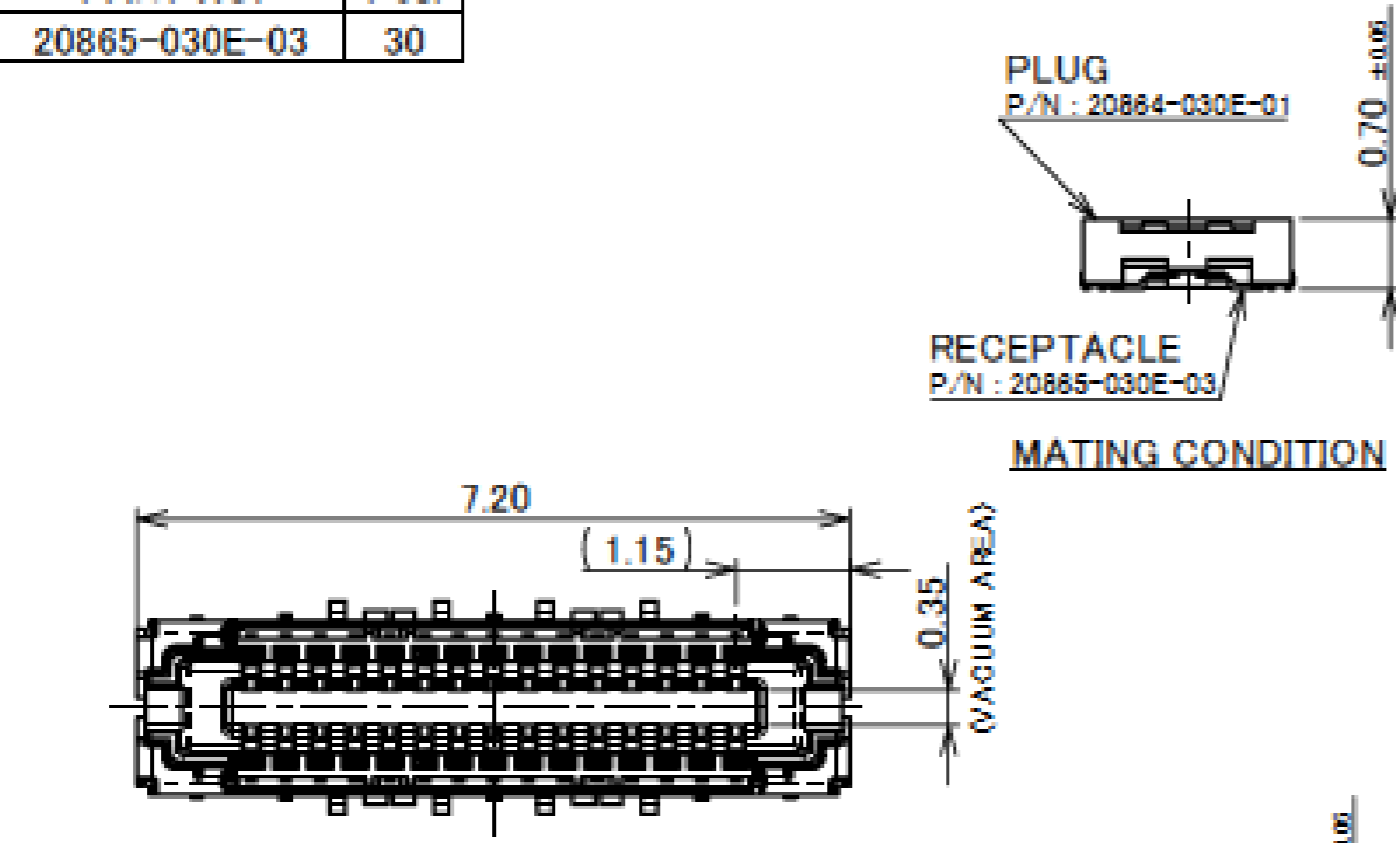
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Rev.9

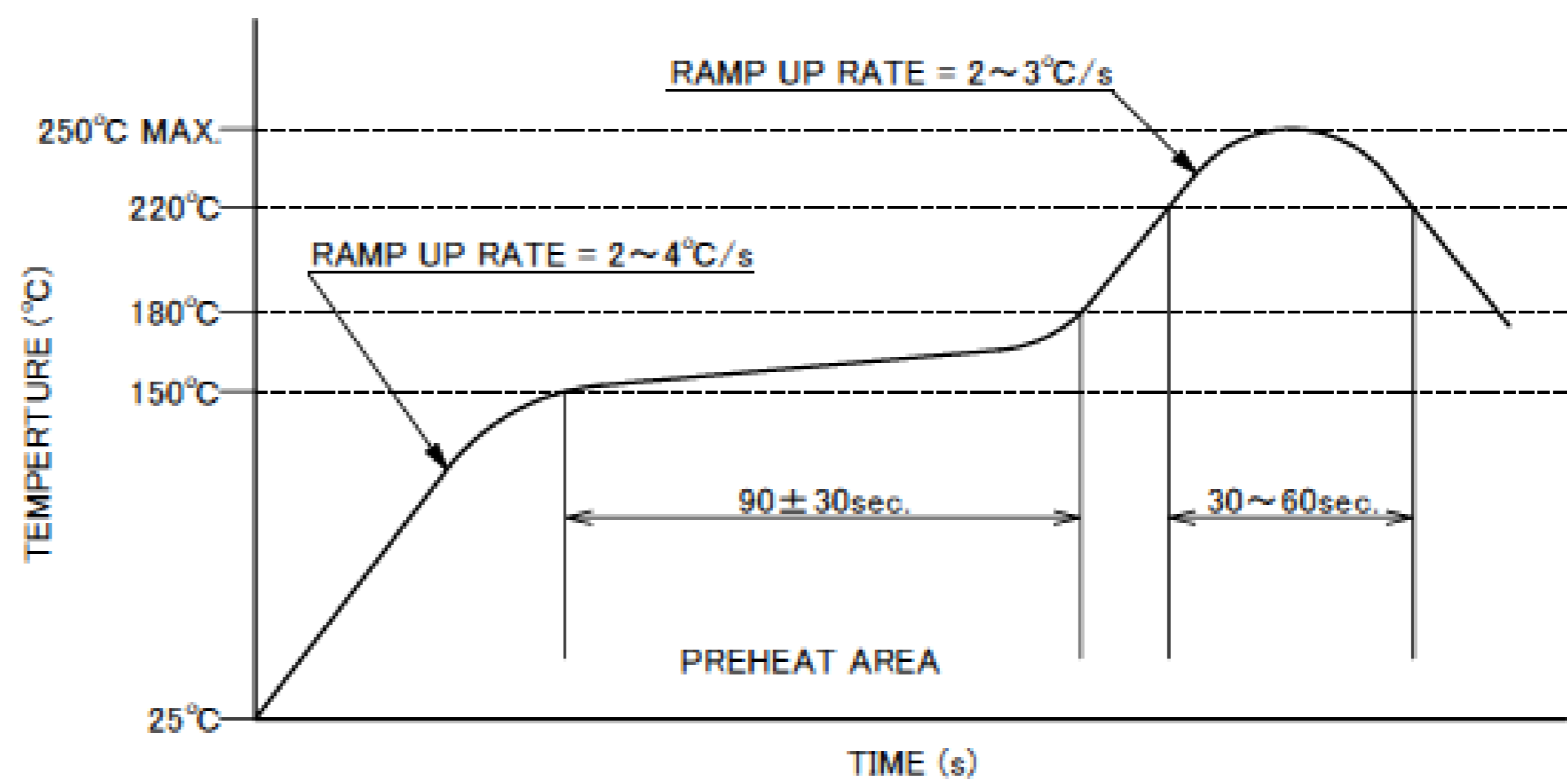
Receptacle Assembly

Recommended P/N		20865-030E-03
PART NO.	Pos.	
20865-030E-03	30	



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1	HOUSING	LCP	UL94V-0 BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

Rev.9

Receptacle Assembly

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OPERATING TEMPERATURE	233~358K(-40°C~85°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENDING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 40mohm MAX. / AFTER TEST : Δ 40mohm MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : Δ 20mohm MAX.
INSULATION RESISTANCE	INITIAL : 1,000Mohm MIN. / AFTER TEST : 500Mohm MIN.
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DURABILITY	10 CYCLES
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UNMATING FORCE (INITIAL / AFTER TEST)	10 CYCLES 0.15N/Pin MIN.
COPLANARITY	0.08 MAX.
PRODUCT SPECIFICATION	PRS-2607
TEST REPORT	TR-19055
PACKING STANDARD	PST-18023
INSTRUCTION MANUAL	HIM-18019
APPEARANCE CRITERIA No.	QLS-A***

Rev.9

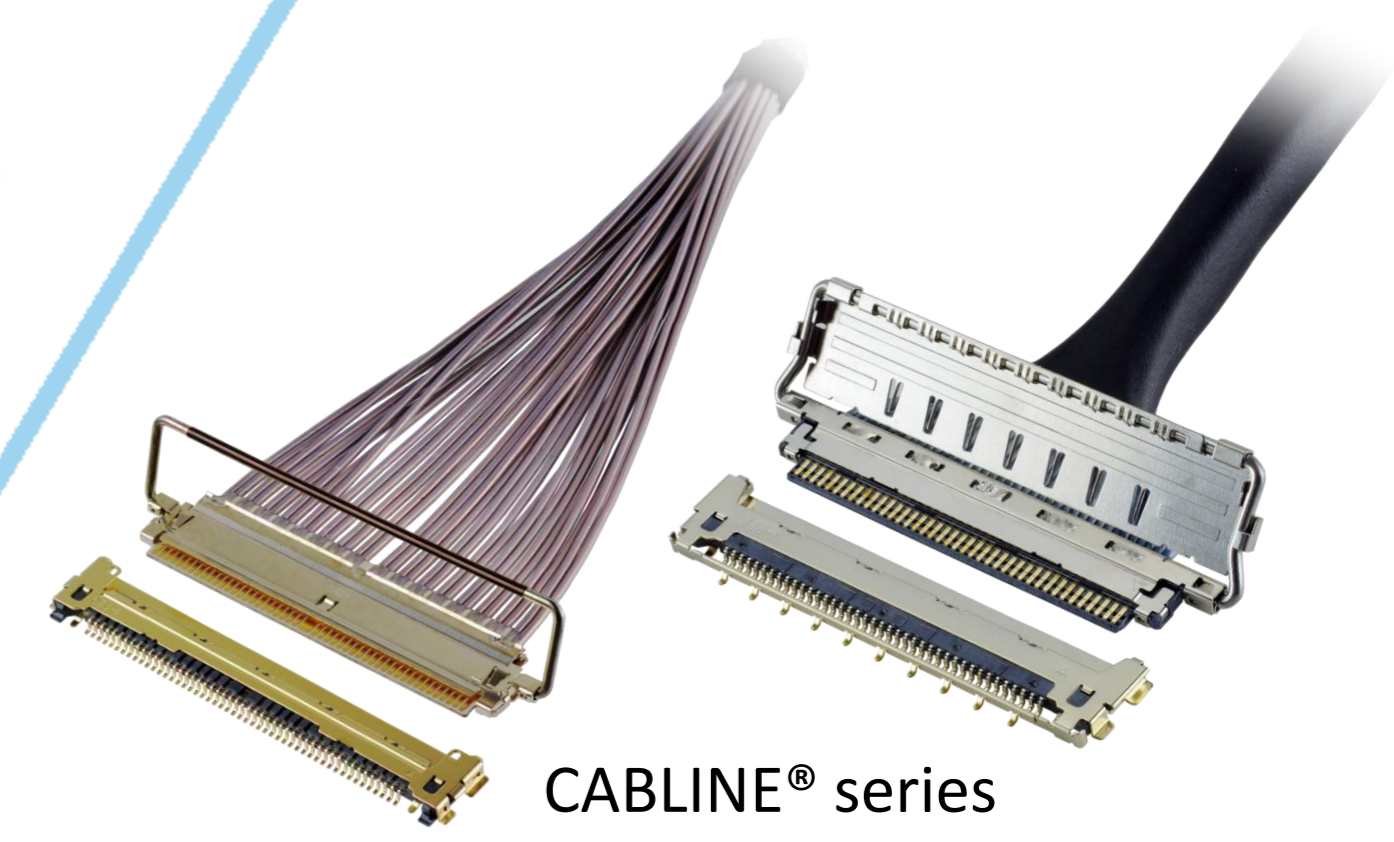
Custom Connectors Available

 RF Connector

MHF® series



CABLINÉ® series
Micro-coaxial/Twinax/
Discrete Wire Connector



Optical Module

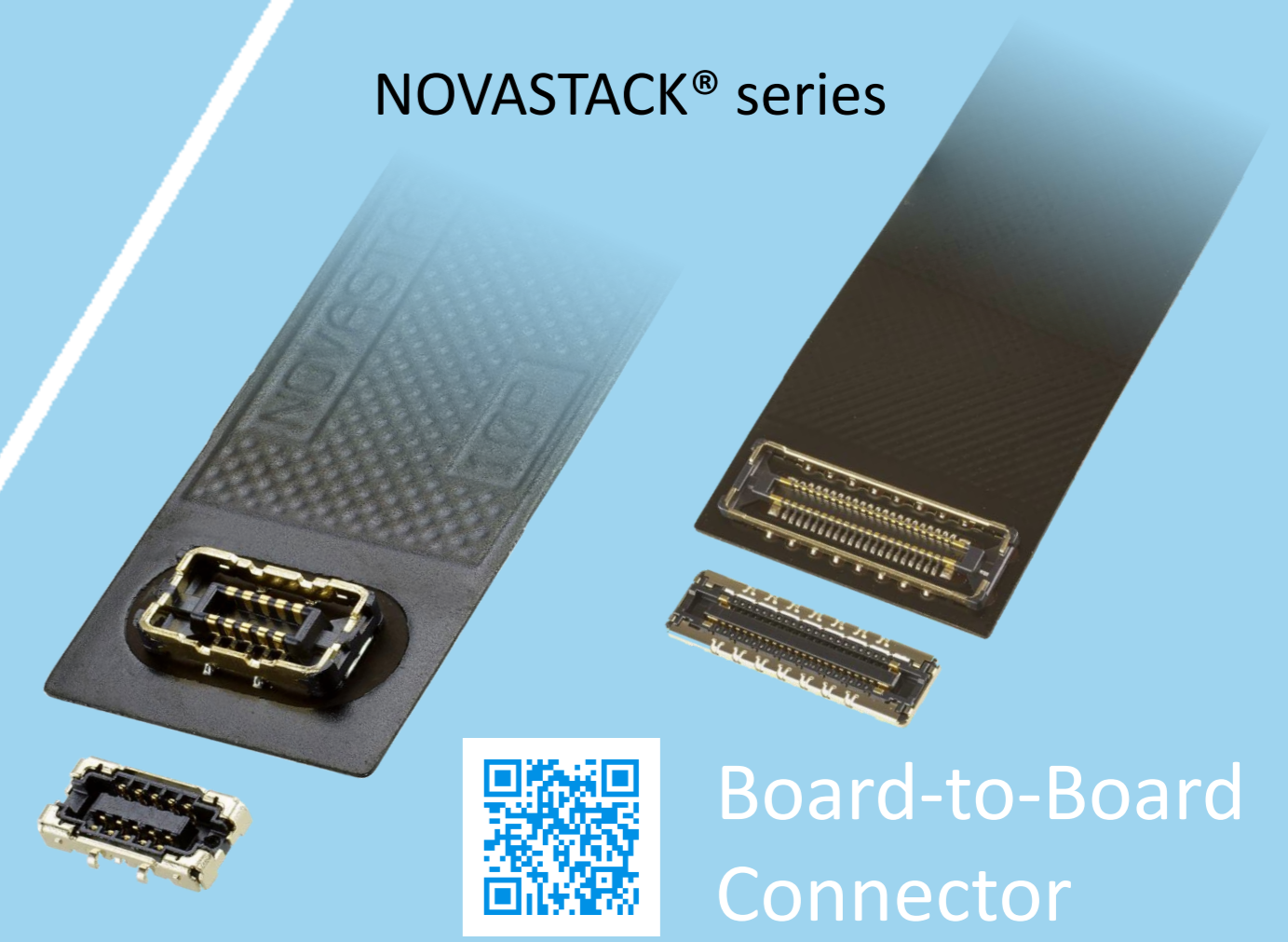
LIGHTPASS® series



NOVASTACK® series



Board-to-Board Connector



Power Connector/
Terminal

AP series

ISH® series



MINIFLEX® series

EVAFLEX® series



FPC FFC Connector



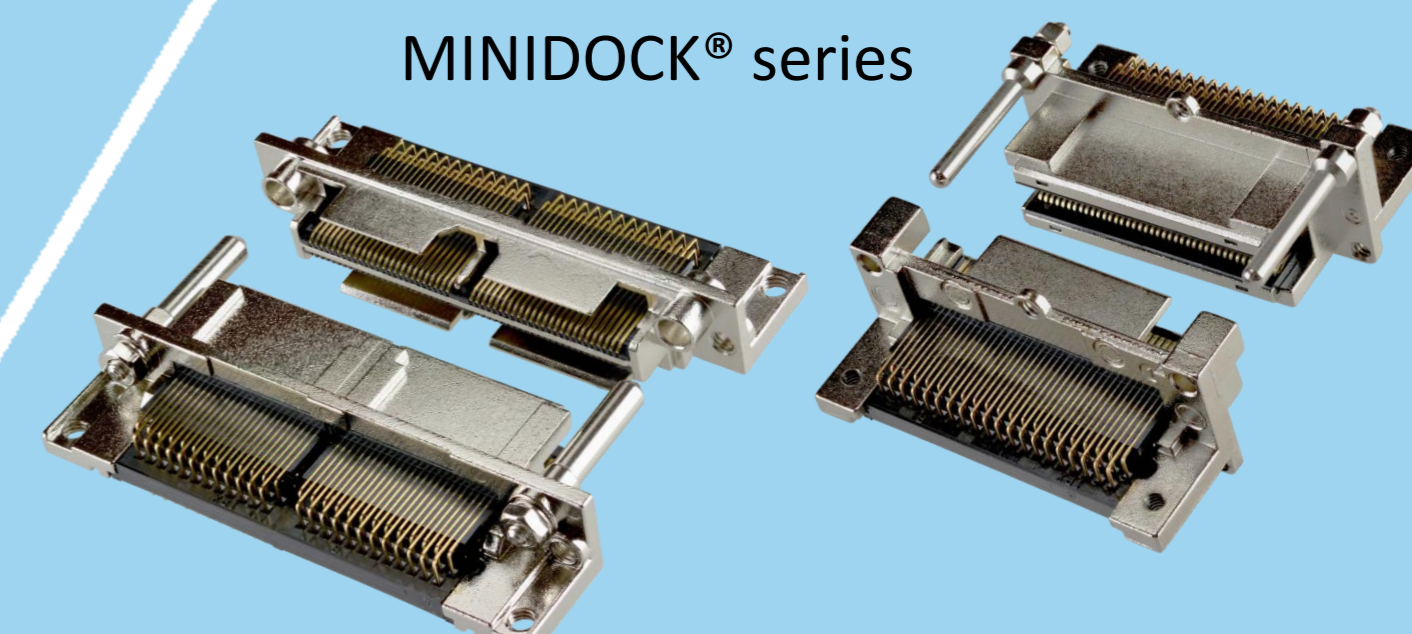
Inquiry



MINIDOCK® series



I/O Connector



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Contact your sales representative or more detailed information.

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